

General Description

The WSD20L100DN56 is the highest performance trench P-Channel MOSFET with extreme high cell density, which provide excellent $R_{DS(ON)}$ and gate charge for most of the synchronous buck converter applications.

The WSD20L100DN56 meet the RoHS and Green Product requirement 100% E_{AS} guaranteed with full function reliability approved.

Features

- Advanced high cell density Trench technology
- Super Low Gate Charge
- Excellent CdV/dt effect decline
- 100% E_{AS} Guaranteed
- Green Device Available

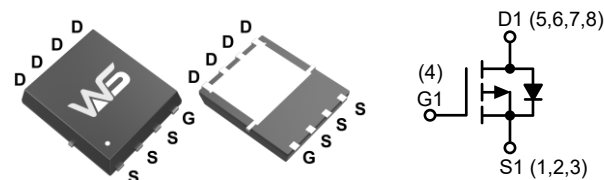
Product Summary

BV_{DSS}	$R_{DS(ON)}$	I_D
-20V	3.5m Ω	-100A

Applications

- High Frequency Point-of-Load Synchronous Buck Converter for MB/NB/UMPC/VGA
- Networking DC-DC Power System
- Load Switch

DFN5X6-8L Pin Configuration



Absolute Maximum Ratings

Symbol	Parameter	Rating	Units
V_{DS}	Drain-Source Voltage	-20	V
V_{GS}	Gate-Source Voltage	± 12	
$I_D @ T_C = 25^\circ C$	Continuous Drain Current, $V_{GS} @ -10V$ ¹	-100	A
$I_D @ T_C = 100^\circ C$	Continuous Drain Current, $V_{GS} @ -10V$ ¹	-46	
I_{DM}	Pulsed Drain Current ²	-290	
E_{AS}	Single Pulse Avalanche Energy ³	320	mJ
$P_D @ T_C = 25^\circ C$	Total Power Dissipation ⁴	40	W
$P_D @ T_C = 100^\circ C$	Total Power Dissipation ⁴	16	
T_{STG}	Storage Temperature Range	-55 to 150	$^\circ C$
T_J	Operating Junction Temperature Range	-55 to 150	

Thermal Data

Symbol	Parameter	Typ.	Max.	Units
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient ¹	---	60	$^\circ C/W$
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient ¹ ($t \leq 10s$)	---	55	
$R_{\theta JC}$	Thermal Resistance, Junction-to-Case ¹	---	3.1	

Electrical Characteristics ($T_J=25^{\circ}\text{C}$, Unless Otherwise Noted)

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Units
BV_{DSS}	Drain-Source Breakdown Voltage	$V_{GS}=0V$, $I_D=-250\mu A$	-20	---	---	V
$\Delta BV_{DSS}/\Delta T_J$	BV_{DSS} Temperature Coefficient	Reference to 25°C , $I_D=-1mA$	---	-0.0212	---	V/ $^{\circ}\text{C}$
$R_{DS(ON)}$	Static Drain-Source On-Resistance ²	$V_{GS}=-4.5V$, $I_D=-25A$	---	3.5	4.7	m Ω
		$V_{GS}=-2.5V$, $I_D=-20A$	---	5.0	7.5	
$V_{GS(th)}$	Gate Threshold Voltage	$V_{GS}=V_{DS}$, $I_D=-250\mu A$	-0.4	-0.6	-1.0	V
$\Delta V_{GS(th)}$	$V_{GS(th)}$ Temperature Coefficient		---	4.8	---	mV/ $^{\circ}\text{C}$
I_{DSS}	Zero Gate Voltage Drain Current	$V_{DS}=-20V$, $V_{GS}=0V$, $T_J=25^{\circ}\text{C}$	---	---	-1.0	μA
		$V_{DS}=-20V$, $V_{GS}=0V$, $T_J=55^{\circ}\text{C}$	---	---	-6.0	
I_{GSS}	Gate-Body Leakage Current	$V_{GS}=\pm 12V$, $V_{DS}=0V$	---	---	± 100	nA
g_{fs}	Forward Transconductance	$V_{DS}=-5V$, $I_D=-20A$	---	60	---	S
R_g	Gate Resistance	$V_{DS}=0V$, $V_{GS}=0V$, $f=1.0MHz$	---	2.0	5.0	Ω
Q_g	Total Gate Charge(-4.5)	$V_{DS}=-10V$, $V_{GS}=-4.5V$, $I_D=-25A$	---	87	---	nC
Q_{gs}	Gate-Source Charge		---	8	---	
Q_{gd}	Gate-Drain Charge		---	22	---	
$T_{d(on)}$	Turn-On Delay Time	$V_{DD}=-10V$, $V_{GEN}=-4.5V$, $R_G=3\Omega$, $I_D=-1A$, $R_L=0.5\Omega$	---	18	---	ns
T_r	Rise Time		---	20	---	
$T_{d(off)}$	Turn-Off Delay Time		---	250	---	
T_f	Fall Time		---	96	---	
C_{iss}	Input Capacitance	$V_{DS}=-10V$, $V_{GS}=0V$, $f=1.0MHz$	---	6100	---	pF
C_{oss}	Output Capacitance		---	1100	---	
C_{rss}	Reverse Transfer Capacitance		---	980	---	

Guaranteed Avalanche Characteristics

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Units
E_{AS}	Single Pulse Avalanche Energy ⁵	$V_{DD}=-25V$, $L=0.5mH$, $I_{AS}=-60A$	120	---	---	mJ

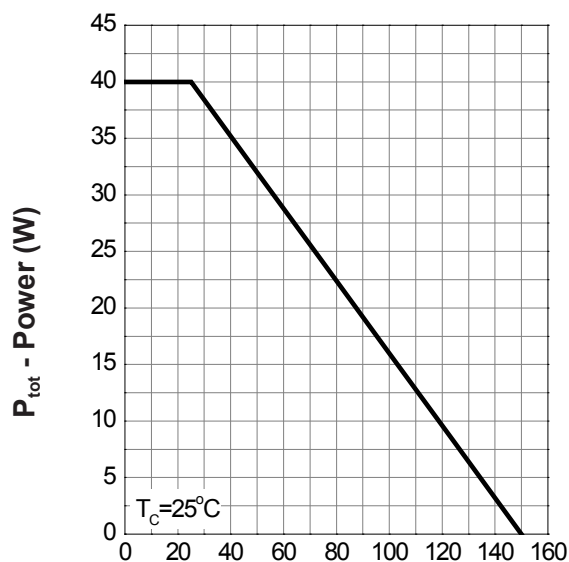
Diode Characteristics

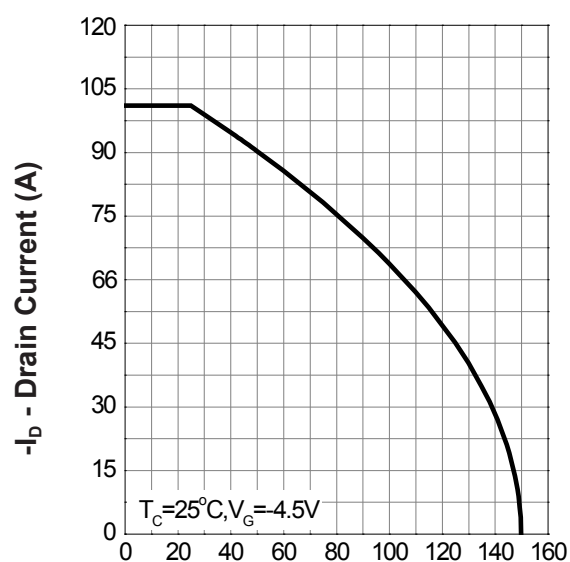
Symbol	Parameter	Conditions	Min.	Typ.	Max.	Units
I_S	Continuous Source Current ^{1,6}	$V_G=V_D=0V$, Force Current	---	---	-36	A
V_{SD}	Diode Forward Voltage ²	$V_{GS}=0V$, $I_S=-1A$, $T_J=25^{\circ}\text{C}$	---	---	-1.2	V
t_{rr}	Reverse Recovery Time	$I_F=-25A$, $dI/dt=100A/\mu s$, $T_J=25^{\circ}\text{C}$	---	48	---	ns
Q_{rr}	Reverse Recovery Charge		---	55	---	nC

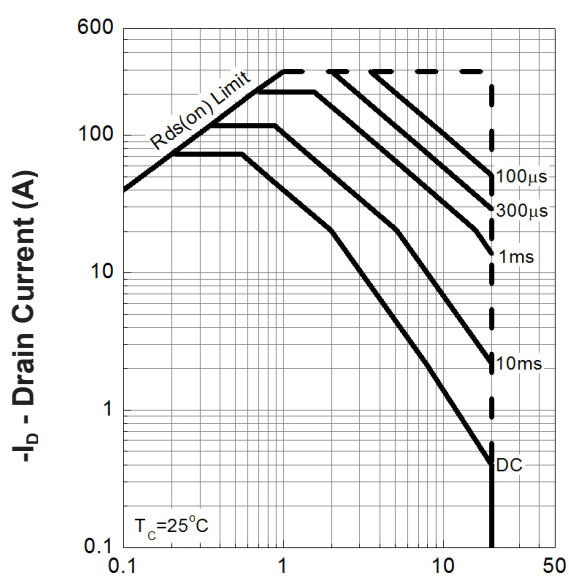
Note:

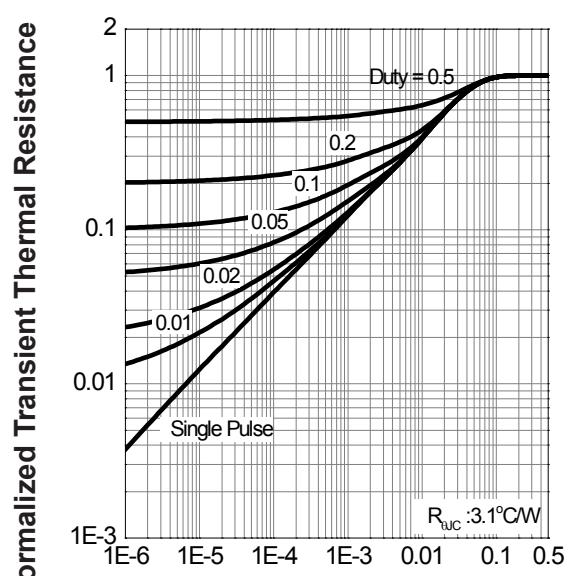
1. The data tested by surface mounted on a 1 inch² FR-4 board with 20Z copper, $t \leq 10\text{sec}$.
2. The data tested by pulsed, pulse width $\leq 300\mu s$, duty cycle $\leq 2\%$
3. The E_{AS} data shows Max. rating. The test condition is $V_{DD}=-10V$, $V_{GS}=-4.5V$, $L=0.5mH$, $I_{AS}=-60A$
4. The power dissipation is limited by 150°C junction temperature.
5. The Min. value is 100% E_{AS} tested guarantee.
6. The data is theoretically the same as I_D and I_{DM} , in real applications, should be limited by total power dissipation.

Typical Characteristics

Power Dissipation

 T_j - Junction Temperature ($^{\circ}\text{C}$)

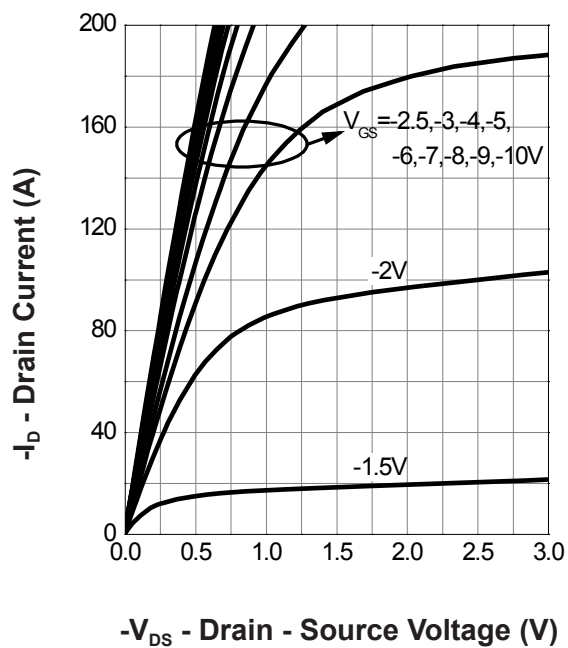
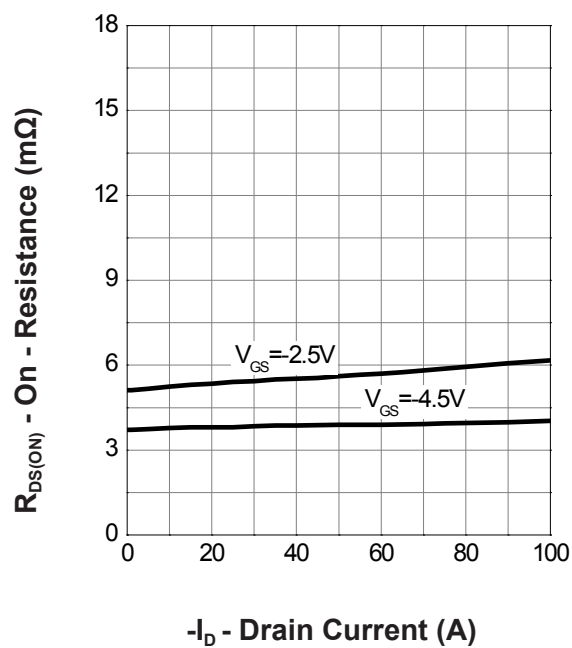
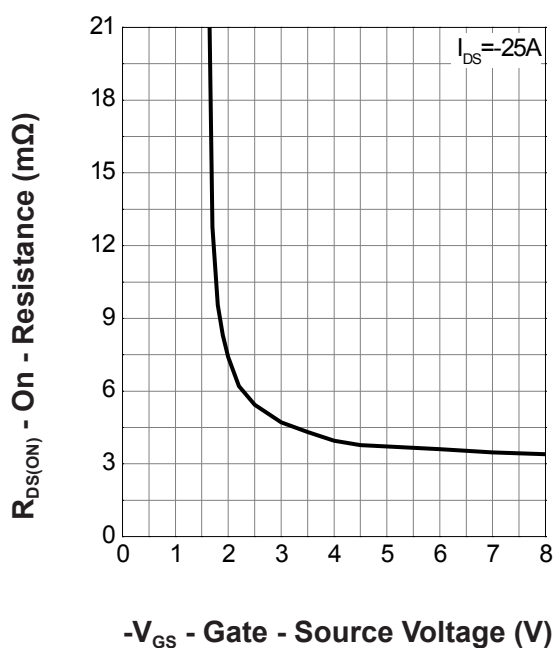
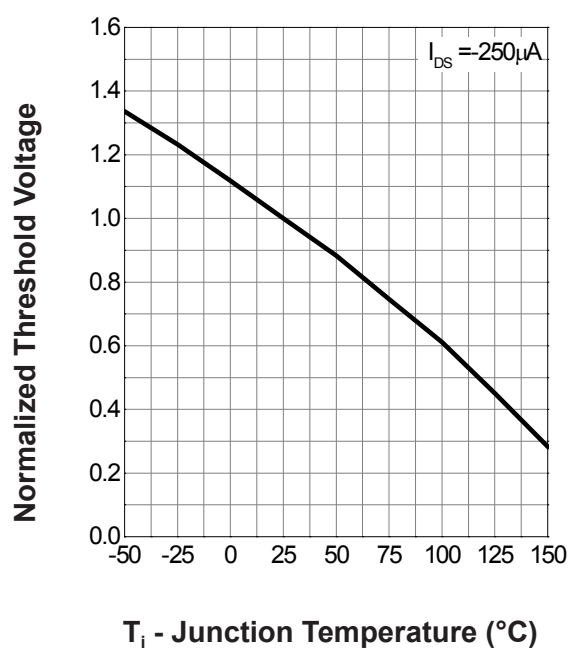
Drain Current

 T_j - Junction Temperature ($^{\circ}\text{C}$)

Safe Operation Area

 $-V_{DS}$ - Drain - Source Voltage (V)

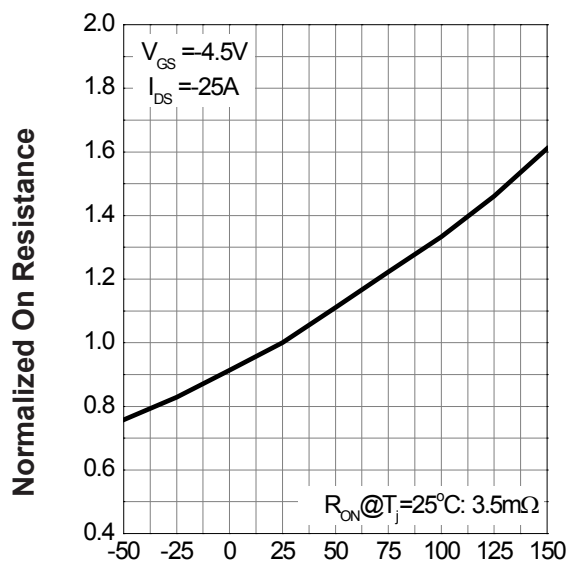
Thermal Transient Impedance


Square Wave Pulse Duration (sec)

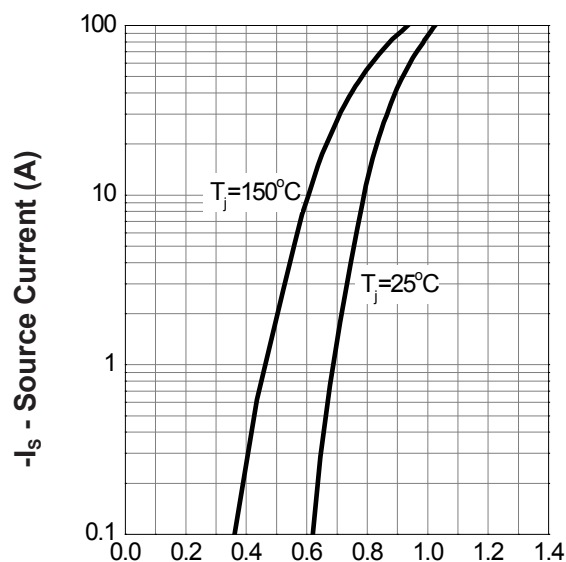
Typical Characteristics (Cont.)

Output Characteristics

Drain-Source On Resistance

Gate-Source On Resistance

Gate Threshold Voltage


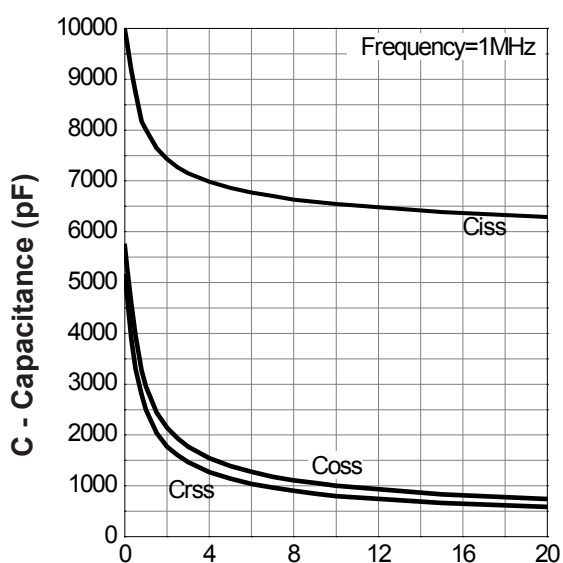
Typical Characteristics (Cont.)

Drain-Source On Resistance


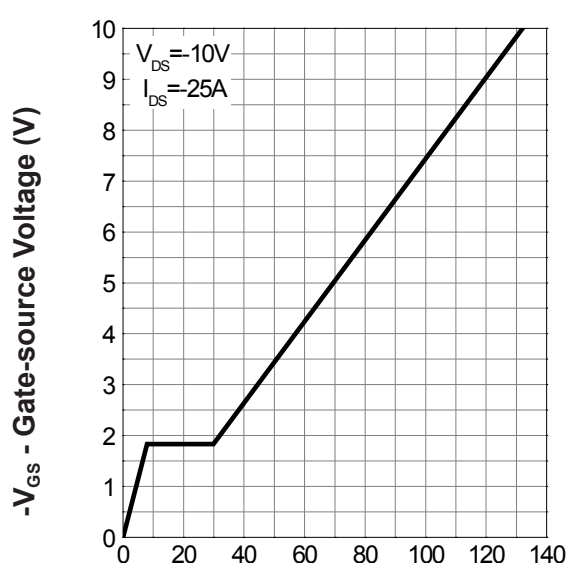
T_j - Junction Temperature ($^{\circ}\text{C}$)

Source-Drain Diode Forward


$-V_{SD}$ - Source - Drain Voltage (V)

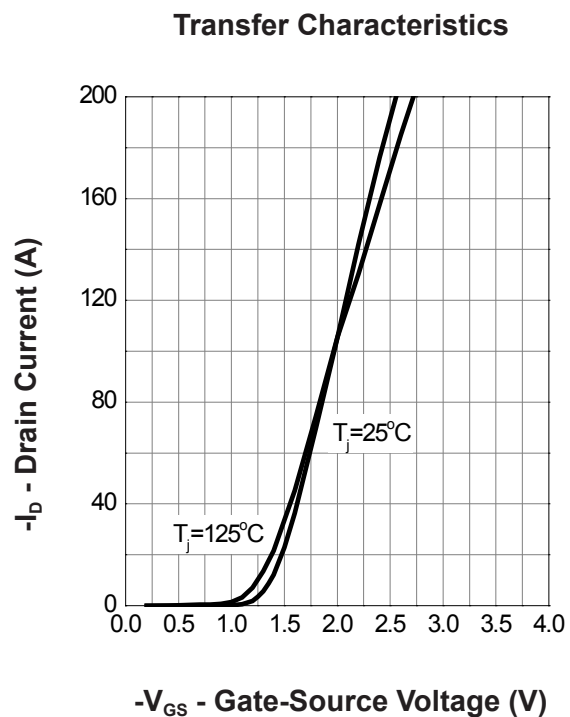
Capacitance


$-V_{DS}$ - Drain-Source Voltage (V)

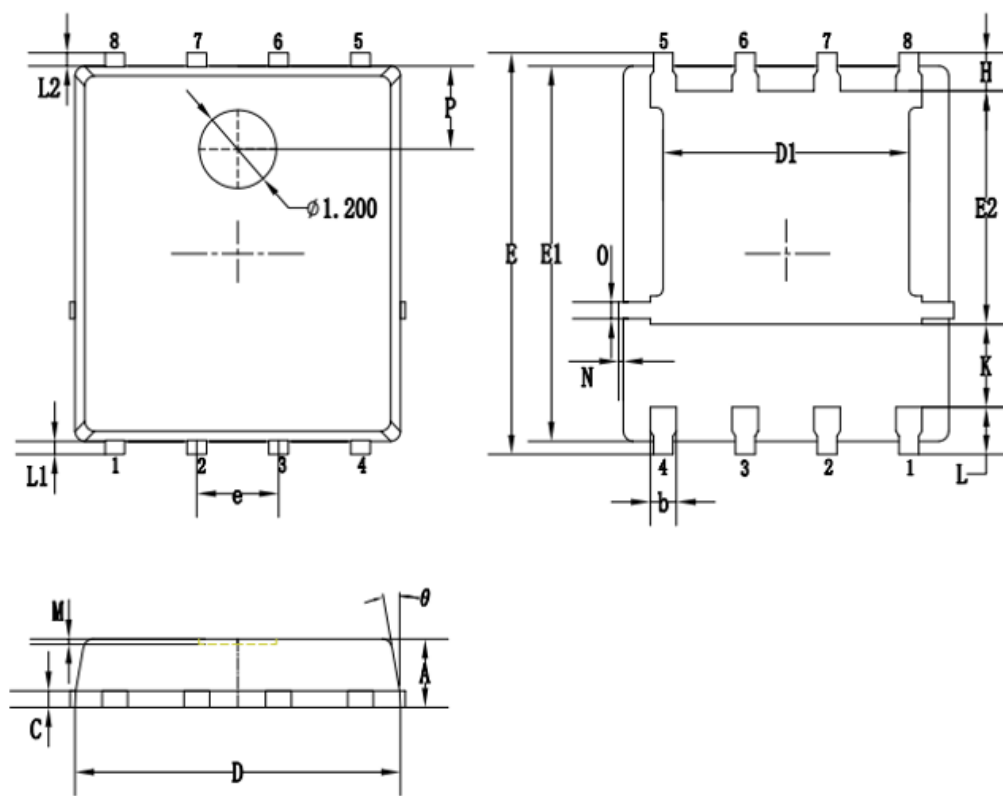
Gate Charge


Q_G - Gate Charge (nC)

Typical Characteristics (Cont.)



Packaging information



SYMBOLS	MILLIMETERS		
	MIN.	NOM.	MAX.
A	0.90	1.05	1.20
b	0.35	0.40	0.50
C	0.20	0.25	0.35
D	4.90	5.05	5.20
D1	3.72	3.82	3.92
E	6.00	6.15	6.30
E1	5.60	5.75	5.90
E2	3.47	3.57	3.67
e	1.27 BSC.		
H	0.48	0.58	0.68
K	1.17	1.27	1.37
L	0.64	0.74	0.84
L1/L2	0.20 REF.		
θ	8°	10°	12°
M	0.08 REF.		
N	0	-	0.15
O	0.25 REF.		
P	1.28 REF.		

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